

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com

Product image



















Similar to illustration

High-temperature resistant, double level, laterally offset, closed ended male header, with solder flange option.

1.5 mm solder pin suitable for reflow soldering. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded.

General ordering data

Version	PCB plug-in connector, male header, Flange / Solder flange, THT/THR solder connection, 5.00 mm, Number of poles: 32, 180°, Solder pin length (I): 1.5 mm, tinned, black, Box
Order No.	<u>1895600000</u>
Туре	SLDV-THR 5.00/32/180FLF 1.5SN BK BX
GTIN (EAN)	4032248510344
Qty.	10 pc(s).
Product data	IEC: 400 V / 15 A UL: 300 V / 10 A
Packaging	Box

Creation date March 26, 2021 5:58:04 AM CET



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Technical data

Dimensions and weights

Depth	23.43 mm	Depth (inches)	0.922 inch
Height	27.66 mm	Height (inches)	1.089 inch
Height of lowest version	26.16 mm	Net weight	22.962 g
Width	90 mm	Width (inches)	3.543 inch

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.00	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5 mm
Pitch in inches (P)	0.197 inch	Outgoing elbow	180°
Number of poles	32	Number of solder pins per pole	1
Solder pin length (I)	1.5 mm	Solder pin length tolerance	+0.1 / -0.2 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,03 mm
Solder eyelet hole diameter (D)	1.5 mm	Solder eyelet hole diameter tolerance (D)+ 0,1 mm	
L1 in mm	75 mm	L1 in inches	2.953 inch
Number of rows	2	Pin series quantity	2
Touch-safe protection acc. to DIN VDE 57 106	finger-safe plugged/ back- of-hand-safe unplugged	Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	9 N	Pulling force/pole, max.	8 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuSn
Contact surface		Layer structure of solder connection	13 μm Ni / 24 μm Sn
	tinned		matt
Layer structure of plug contact	13 μm Ni / 24 μm Sn	Storage temperature, min.	
	matt		-40 °C
	matt		10 0
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Storage temperature, max. Operating temperature, max.		Operating temperature, min. Temperature range, installation, min.	

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	10.5 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	9 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV	Short-time withstand current resistance	1 x 1s with 120 A



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Technical data

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	
Tistitute (CSA)	α	Certificate No. (CSA)	
	(SP°		
	•		200039-1121690
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	10 A	Rated current (Use group D / CSA)	10 A
Reference to approval values	Specifications are		
	maximum values, details - see approval certificate.		
Rated data acc. to UL 1059			
nstitute (UR)	<i>511</i>	Certificate No. (UR)	
			E60693
Institute (cURus)	- 71	Certificate No. (cURus)	
			E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	
Rated current (Use group B / UL 1059)		Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Packing			
	n.	VDE	F0
Packaging /PE width	Box 100 mm	VPE length VPE height	50 mm 175 mm
/FE Width	100 mm	VFE Height	175 11111
Classifications			
ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
mportant note			
PC conformity	standards and norms and comp	eveloped, manufactured and delivered according ly with the assured properties in the data sheet of Class 2". Further claims on the products can be of	esp. fulfill decorative propert
Notes	Rated current related to rated	cross-section & min. No. of poles.	
	Spacing between rows: see h	ole layout	
	• P on drawing = pitch		
		omponent itself. Clearance and creepage distance ith the relevant application standards.	ces to other components are

• Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months



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Technical data

Approvals

Approvals



ROHS	Conform	
UL File Number Search	E60693	

Downloads

Approval/Certificate/Document of	
Conformity	Declaration of the Manufacturer
Engineering Data	STEP



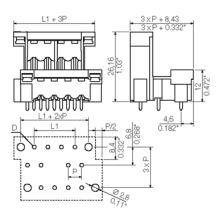
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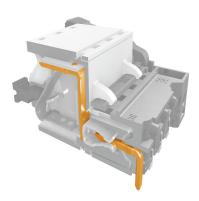
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Drawings

Dimensional drawing



Product benefits



Safe power transmission Proven properties



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Drawings

Product benefits



L1+15 +0.05 DIE DEUTSCHE VERSION IST VERBINDLICH 23.43 **Technical Data** 0.922" THE GERMAN VERSION IS BINDING L1+0.591" Rev. Material data LCP GF Insulation material type Insulation material colours black шш Insulation material flammability class UL94 V-0 Insulation resistance MOhm 10 Contact base material CuSn Contact plating (mating end) tin plated Contact plating (solder end) tin plated 26.16 1.03 System characteristic values together with counterpart BLZ 5.00 Pitch P 5.00/0.197 mm/inch шш ш 12 Number of rows Dielectric strength (r.m.s withstand voltage) kV Mechanical operating cycles acc. to IEC 512 25 Plug in force (max.) N/pole n.a. Pull out force (max.) N/pole n.a. Through resistance (typical) <5 mOhm -55...+100 Operating temperature range °C Degree of protection acc. to VDE 0106 (plugged/unplugged) back of hands 6.78 Degree of protection acc. to DIN EN 60529 (plugged/unplugged) IP10 L1 + 100.267 Solder pin length L 3.2/0.126 ; 1.5/0.059 mm/inch M2.5 15 4.6 PCB hole diameter **D** (wave soldering) L1 + 0.3941.4/0.055 mm/inch 0.591 0.182" PCB hole diameter **D** (reflow soldering) mm/inch 1.5/0.059 Resistance to soldering heat acc. to DIN IEC 60512-6 260/5 °C/sec 8.4 Resistance to soldering heat acc. to EN 61760-1 °C/sec 290/30 Solderability classification acc. to EN 61760-1 class A through hole solder Solder connection type Solder pin diameter d (max.) mm/inch 1.2/0.047 **Application notes** Coding possibility yes/no Joinable without loss of pitch yes/no n.a. Manual assembly of modules yes/no n.a. Max. number of poles n 48 115,00 4,53 IEC 664-1 / VDE0110 (4.97) rated data 46 110,00 4,33 Rated cross section acc. to EN 60999 mm² n.a. L1 + 17.544 105,00 4,13 Rated current @ 20°C ambient (together with BLZ5.08) Α 18.6 42 100,00 3,94 Rated current @ 40°C ambient (together with BLZ 5.08) _A_ 16.1 L1 + 0.689Overvoltage category / Pollution degree III/3 III/2 11/2 40 95,00 3,74 320 L1 + 10250 Rated voltage 400 L1 + 1038 90,00 3,54 4.0 Rated impulse voltage kV 4.0 4.0 L1 + 0.394L1 + 0.3940.039" 36 85,00 3,35 File No.: E60693 L1 2.5 0.5 UL 1059 rated data В 0 34 80,00 3,15 Rated voltage V 300 300 0.098 0.02 32 75,00 2,95 10 Rated current Α 10 30 70,00 2,76 AWG wire range (field wiring / factory wiring) n.a. 332 28 65,00 2,56 **(**+) **①** File No.: 12400(1308147)B CSA C22.2 rated data 26 60,00 2,36 300 6.8 Rated voltage ٧ 300 0 24 2,17 55,00 Rated current 10 10 15 AWG wire range (field wiring / factory wiring) 22 1,97 n.a. 0 43 50,00 \oplus **(①** \oplus **(** ⊕ 29 20 45,00 1,77 ၈ **Packaging** carton 0 S 0 1,57 2.5 2.5 18 40,00 **Downloads** www.weidmueller.de 0.098 0.098 16 35,00 1,38 **(**+) \oplus \bigoplus 14 30,00 1,18 0,98 12 25,00 10 20,00 0,79 **′**0∙ Ρ 4x optional 2.5 8 15,00 0,59 for screws 0.098 10,00 0,39 Layout Finished Holes Paste-Free Area 4 5,00 0,20 1) Sum of ambient temperature and temperature rise SLDV-THR 5.00/12/180FLF shown: L1[mm] L1 [inch] 2) Recommendation for manual assembly For the mounting of PCBs, it should be noted that the 3) Recommendation for automatic assembly **METRIC TOLERANCES** rated data given in the catalogue relates only to the 4) Recommendation for wave soldering connection elements. The neccessary creepage and $X_{\cdot} = \pm 0.3$ 37601/5 07.09.07 HERTEL_S 01 5) Recommendation for reflow soldering Weidmüller 🌫 clearance paths must be observed in connection with $X.X = \pm 0.1$ 6) Referred to rated cross section and minimum pole number the respective applicant in accordance to VDE 0110. 7) Fingersafe above PC-board, if plugged with BLZ $X.XX = \pm 0.05 RoHS \ \overline{V}$ The current-carrying capacity and pitch tolerance is to MODIFICATION be determined according to DIN IEC 326 part 3 very fine. 8) IP20 above PC-board, if plugged with BLZ NAME DATE Weidmüller connectors are tested to the DIN VDE 0627 n.a. = not applicable SLDV-THR 5.00/../180 FLF IDRAWN 04.08.2004 HERTEL S standard, and are valid for its field of application. Provided that the connectors are used to the intended SCALE: 2:1 RESPONSIBLE Subject to technical changes Stiftleiste purpose, all requirements with respect to the SUPERSEDES: CHECKED 13.09.2007 HERTEL S Pin header occuring of electrical, mechanical, thermic and corrosive stress will be satisfied. APPROVED SUPERSEDED BY: PRODUCT FILE: SLDV-THR 5.08 None



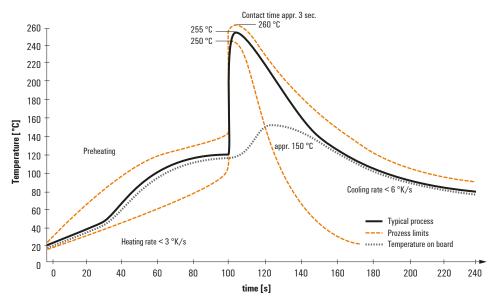
Recommended wave solderding profiles

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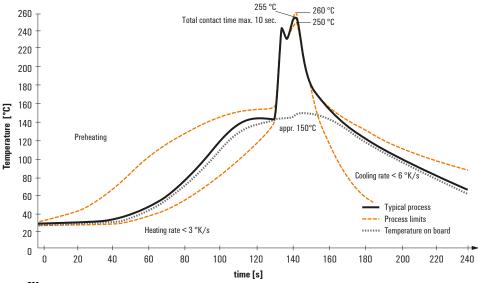
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

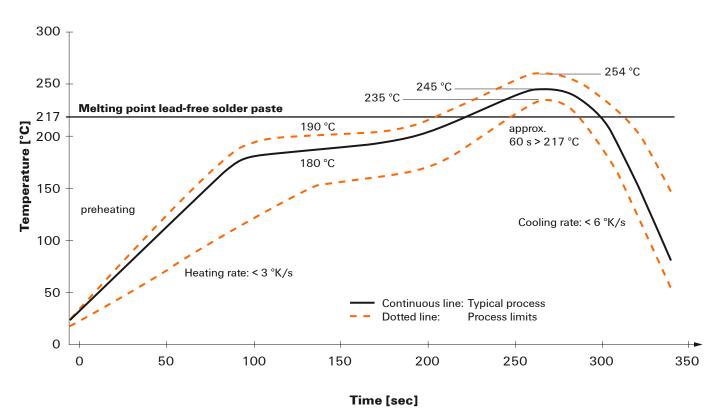


Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- · Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.